Electrically Insulating, Thermally Conductive Phase Change Material

### **Features and Benefits**

- Thermal impedance: 0.71°C-in²/W (@25 psi)
- · Electrically isolating
- 65°C phase change compound coated on PEN film
- Tack free and scratch resistant



Hi-Flow 625 is a film-reinforced phase change material. The product consists of a thermally conductive 65°C phase change compound coated on PEN film. Hi-Flow 625 is designed to be used as a thermal interface material between electronic power devices that require electrical isolation and a heat sink. The reinforcement makes Hi-Flow 625 easy to handle, and the 65°C phase change temperature of the coating material eliminates shipping and handling problems. The PEN film has a continuous use temperature of 150°C.

Hi-Flow 625 is tack free and scratch resistant at production temperature and does not require a protective liner in most shipping situations. The material has the thermal performance of 2-3 mil mica and grease assemblies.

TYPICAL PROPERTIES OF HI-FLOW 625					
IMPERIAL VALUE		METRIC VALUE		TEST METHOD	
Green		Green		Visual	
PEN Film		PEN Film		_	
0.005		0.127		ASTM D374	
60		60		ASTM D882A	
30,000		206		ASTM D882A	
302		150		_	
149		65		DSC	
4000		4000		ASTM D149	
3.5		3.5		ASTM D150	
1010		1010		ASTM D257	
94 V-O		94 V-O		U.L.	
0.5		0.5		ASTM D5470	
URE					
ure (psi)	10	25	50	100	200
Performance (°C/W)		2.10	2.00	1.93	1.87
<sup>2</sup> /W) (2)	0.79	0.71	0.70	0.67	0.61
	### IMPERIAL Green	MPERIAL VALUE	MPERIAL VALUE   METRIC	IMPERIAL VALUE         METRIC VALUE           Green         Green           PEN Film         PEN Film           0.005         0.127           60         60           30,000         206           302         150           149         65           4000         4000           3.5         3.5           10°         10°           94 V-O         94 V-O           URE         URE           ure (psi)         10         25         50           2 (°C/VV)         2.26         2.10         2.00	IMPERIAL VALUE         METRIC VALUE         TEST M           Green         Green         Vis           PEN Film         PEN Film         -           0.005         0.127         ASTM           60         60         ASTM           30,000         206         ASTM           302         150         -           149         65         Di           4000         4000         ASTM           3.5         3.5         ASTM           94 V-O         94 V-O         U           0.5         0.5         ASTM           URE         URE         URE           Urre (psi)         10         25         50         100           2 (°C/W)         2.26         2.10         2.00         1.93

I) This is the measured thermal conductivity of the Hi-Flow coating. It represents one conducting layer in a three-layer laminate. The Hi-Flow coatings are phase change compounds. These layers will respond to heat and pressure induced stresses. The overall conductivity of the material in post-phase change, thin film products is highly dependent upon the heat and pressure applied. This characteristic is not accounted for in ASTM D5470. Please contact Bergquist Product Management if additional specifications are required. 2) The ASTM D5470 (Bergquist modified) test fixture was used and the test sample was conditioned at 70°C prior to test. The recorded value includes interfacial thermal resistance. These values are provided for reference only. Actual application performance is directly related to the surface roughness, flatness and pressure applied.

# **Typical Applications Include:**

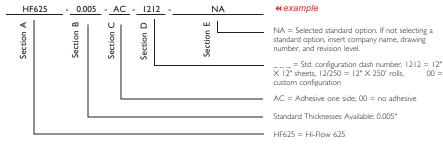
- Spring / clip mounted
- Power semiconductors
- Power modules

# **Configurations Available:**

- Sheet form, die-cut parts and roll form
- With or without pressure sensitive adhesive

### **Building a Part Number**

# **Standard Options**



Note: To build a part number, visit our website at www.bergquistcompany.com.

Hi- Flow®: U.S. Patent 5,950,066 and others



#### www.bergquistcompany.com